

P-Channel Enhancement Mode MOSFET

Description

The SM3020PSUC-TRG uses advanced trench technology to

provide excellent R_{DS(ON)}, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

General Features

 $V_{DS} = -30V I_{D} = 50 A$

 $R_{DS(ON)}$ < 18m Ω @ V_{GS} =10V

Application

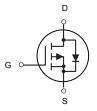
Battery protection

Load switch

Uninterruptible power supply



TO-252-2L (DPAK)



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Brand	Qty(PCS)
SM3020PSUC-TRG	TO-252-2L(DPAK)	HXY MOSFET	2500

Absolute Maximum Ratings (T_C=25°Cunless otherwise noted)

Symbol	Parameter	Rating	Units		
VDS	Drain-Source Voltage	-30	V		
Vgs	Gate-Source Voltage	Gate-Source Voltage ±20			
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ -10V ¹	-50	Α		
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ -10V ¹	_			
ID@T _A =25°C	Continuous Drain Current, V _{GS} @ -10V ¹				
ID@Ta=70°C	0°C Continuous Drain Current, V _{GS} @ -10V ¹ -7.7		А		
Ірм	Pulsed Drain Current ²	Pulsed Drain Current ² -150			
EAS	Single Pulse Avalanche Energy ³	Single Pulse Avalanche Energy ³ 125			
las	Avalanche Current	Avalanche Current -50			
P _D @T _C =25°C	Total Power Dissipation ⁴	Total Power Dissipation ⁴ 45			
P _D @T _A =25°C	Total Power Dissipation ⁴ 2		W		
Тѕтс	Storage Temperature Range -55 to 150		°C		
TJ	Operating Junction Temperature Range	Operating Junction Temperature Range -55 to 150			
Reja	Thermal Resistance Junction-Ambient ¹ 62		°C/W		
Rejc	Thermal Resistance Junction-Case ¹	2.8	°C/W		



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Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =-250uA	-30			V
△BV _{DSS} /△T	BVDSS Temperature Coefficient	Reference to 25°C , I _D =-1mA	I	-0.0232		V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-10V , I _D =-30A		15	18	m()
	Static Drain-Source On-Resistance-	V _{GS} =-4.5V , I _D =-15A		24	32	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} . In =-250uA	-1.0		-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	VGS=VDS , ID =-250UA		4.6		mV/°C
	Drain Course Lookens Courset	V _{DS} =-24V , V _{GS} =0V , T _J =25°C			-1	•
IDSS	Drain-Source Leakage Current	V _{DS} =-24V , V _{GS} =0V , T _J =55°C			-5	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±25V , V _{DS} =0V			±100	nA
gfs	Forward Transconductance	V _{DS} =-5V , I _D =-30A		30		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		9		Ω
Qg	Total Gate Charge (-4.5V)			22		
Qgs	Gate-Source Charge	V _{DS} =-15V , V _{GS} =-4.5V , I _D =-15A		8.7		nC
Q _{gd}	Gate-Drain Charge			7.2		
T _{d(on)}	Turn-On Delay Time			8		
Tr	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_G =3.3 Ω		73.7		no
T _{d(off)}	Turn-Off Delay Time	I _D =-15A		61.8		ns
T _f	Fall Time			24.4		
Ciss	Input Capacitance			2215		
Coss	Output Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		310		pF
Crss	Reverse Transfer Capacitance			237		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	-		-50	Α
I _{SM}	Pulsed Source Current ^{2,5}	VG-VD-0V, Force Current			-150	Α
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25°C			-1	V
t _{rr}	Reverse Recovery Time	IF=-15A , dI/dt=100A/μs ,	-	19	1	nS
Qrr	Reverse Recovery Charge	T _J =25°C		9		nC

Note

- 1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\,\leq\,300\text{us}$, duty cycle $\,\leq\,2\%$
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V,L=0.1mH, I_{AS} =-50A
- 4. The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

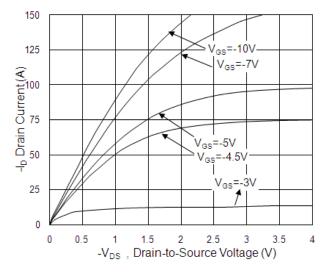


Fig.1 Typical Output Characteristics

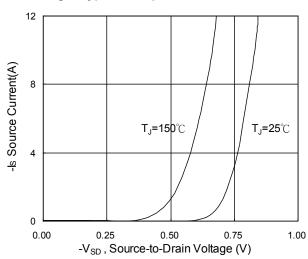


Fig.3 Forward Characteristics of Reverse

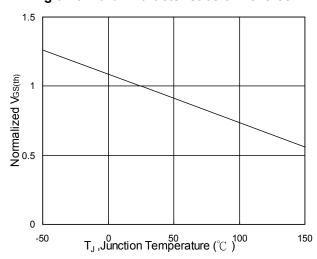


Fig.5 Normalized V_{GS(th)} vs. T_J

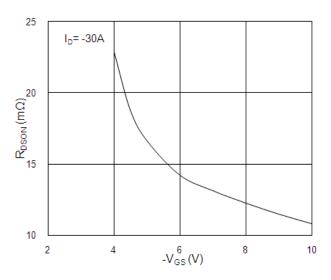


Fig.2 On-Resistance vs. G-S Voltage

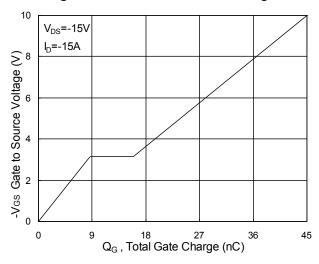


Fig.4 Gate-charge Characteristics

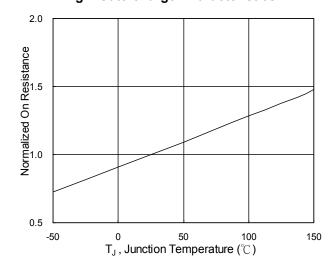
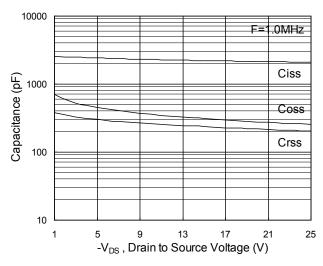


Fig.6 Normalized R_{DSON} vs. T_J



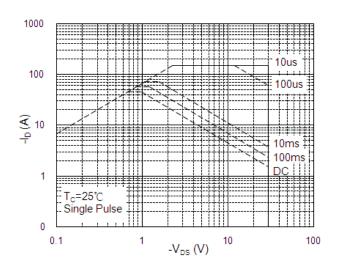


Fig.7 Capacitance

Fig.8 Safe Operating Area

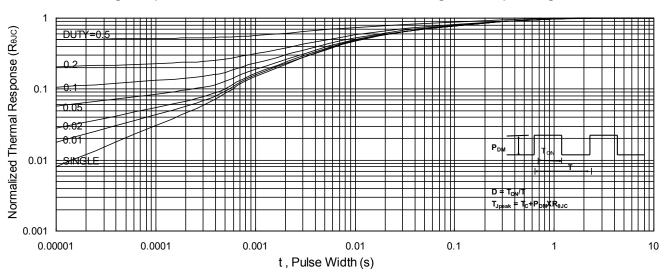


Fig.9 Normalized Maximum Transient Thermal Impedance

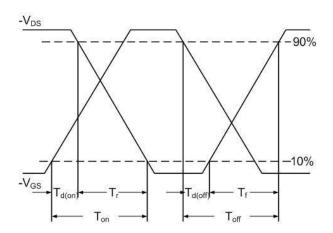


Fig.10 Switching Time Waveform

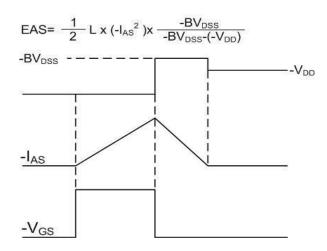
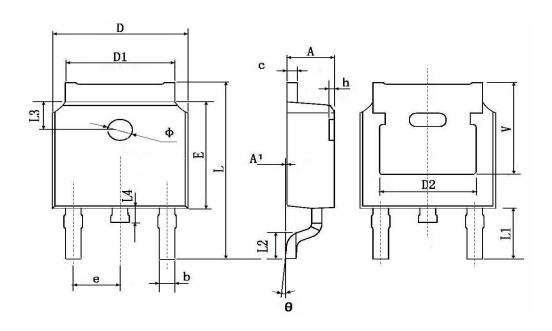


Fig.11 Unclamped Inductive Switching Waveform



TO-252-2L(DPAK) Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min.	Max.	Min.	Max.	
A	2.200	2.400	0.087	0.094	
A1	0.000	0.127	0.000	0.005	
b	0.660	0.860	0.026	0.034	
С	0.460	0.580	0.018	0.023	
D	6.500	6.700	0.256	0.264	
D1	5.100	5.460	0.201	0.215	
D2	4.830	TYP.	0.190 TYP.		
Е	6.000	6.200	0.236	0.244	
е	2.186	2.386	0.086	0.094	
L	9.800	10.400	0.386	0.409	
L1	2.900	TYP.	0.114 TYP.		
L2	1.400	1.700	0.055	0.067	
L3		O TYP.	0.063 TYP.		
L4	0.600	1.000	0.024	0.039	
Ф	1.100	1.300	0.043	0.051	
θ	0°	8°	0°	8°	
h	0.000	0.300	0.000	0.012	
V	5.350	0.211 TYP.		TYP.	

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